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LSM6DSM

iNEMO inertial module: always-on 3D accelerometer and 3D gyroscope

Datasheet - production data

LGA-14L
(2.5 x 3 x 0.83 mm) typ.

Features

- "Always-on" experience with low power consumption for both accelerometer and gyroscope
- Power consumption: 0.4 mA in combo normal mode and 0.65 mA in combo high-performance mode
- Smart FIFO up to 4 kbyte based on features set
- Android M compliant
- Auxiliary SPI for OIS data output for gyroscope and accelerometer
- Hard, soft ironing for external magnetic sensor corrections
- ±2/±4/±8/±16 *g* full scale
- ±125/±245/±500/±1000/±2000 dps full scale
- Analog supply voltage: 1.71 V to 3.6 V
- SPI & I^2C serial interface with main processor data synchronization
- Dedicated gyroscope low-pass filters for UI and OIS applications
- Smart embedded functions: pedometer, step detector and step counter, significant motion and tilt
- Standard interrupts: free-fall, wakeup, 6D/4D orientation, click and double-click
- Embedded temperature sensor
- ECOPACK®, RoHS and "Green" compliant

Applications

- Motion tracking and gesture detection
- Sensor hub
- Indoor navigation
- IoT and connected devices
- Smart power saving for handheld devices
- EIS and OIS for camera applications
- Vibration monitoring and compensation

Description

The LSM6DSM is a system-in-package featuring a 3D digital accelerometer and a 3D digital gyroscope performing at 0.65 mA in high-performance mode and enabling always-on low-power features for an optimal motion experience for the consumer.

The LSM6DSM supports main OS requirements, offering real, virtual and batch sensors with 4 kbyte for dynamic data batching.

ST's family of MEMS sensor modules leverages the robust and mature manufacturing processes already used for the production of micromachined accelerometers and gyroscopes.

The various sensing elements are manufactured using specialized micromachining processes, while the IC interfaces are developed using CMOS technology that allows the design of a dedicated circuit which is trimmed to better match the characteristics of the sensing element.

The LSM6DSM has a full-scale acceleration range of ±2/±4/±8/±16 *g* and an angular rate range of ±125/±245/±500/±1000/±2000 dps.

The LSM6DSM fully supports EIS and OIS applications as the module includes a dedicated configurable signal processing path for OIS and auxiliary SPI configurable for both the gyroscope and accelerometer.

High robustness to mechanical shock makes the LSM6DSM the preferred choice of system designers for the creation and manufacturing of reliable products.

The LSM6DSM is available in a plastic land grid array (LGA) package.

Table 1. Device summary

Part number	Temp. range [°C]	Package	Packing
LSM6DSM	-40 to +85	LGA-14L (2.5x3x0.83mm)	Tray
LSM6DSMTR	-40 to +85		Tape & Reel

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1 Overview

The LSM6DSM is a system-in-package featuring a high-performance 3-axis digital accelerometer and 3-axis digital gyroscope.

The integrated power-efficient modes are able to reduce the power consumption down to 0.65 mA in high-performance mode, combining always-on low-power features with superior sensing precision for an optimal motion experience for the consumer thanks to ultra-low noise performance for both the gyroscope and accelerometer.

The LSM6DSM delivers best-in-class motion sensing that can detect orientation and gestures in order to empower application developers and consumers with features and capabilities that are more sophisticated than simply orienting their devices to portrait and landscape mode.

The event-detection interrupts enable efficient and reliable motion tracking and contextual awareness, implementing hardware recognition of free-fall events, 6D orientation, click and double-click sensing, activity or inactivity, and wakeup events.

The LSM6DSM supports main OS requirements, offering real, virtual and batch mode sensors. In addition, the LSM6DSM can efficiently run the sensor-related features specified in Android, saving power and enabling faster reaction time. In particular, the LSM6DSM has been designed to implement hardware features such as significant motion, tilt, pedometer functions, timestamping and to support the data acquisition of an external magnetometer with ironing correction (hard, soft).

The LSM6DSM offers hardware flexibility to connect the pins with different mode connections to external sensors to expand functionalities such as adding a sensor hub, auxiliary SPI, etc.

Up to 4 kbyte of FIFO with dynamic allocation of significant data (i.e. external sensors, timestamp, etc.) allows overall power saving of the system.

The LSM6DSM fully supports OIS/EIS applications using both the gyroscope and accelerometer sensor. The device can output OIS data through a dedicated auxiliary SPI and includes a dedicated configurable signal processing path for OIS. OIS data can be sent directly to the application processor for data processing. The gyroscope UI signal processing path is completely independent from that of the OIS and is readable through FIFO.

Like the entire portfolio of MEMS sensor modules, the LSM6DSM leverages the robust and mature in-house manufacturing processes already used for the production of micromachined accelerometers and gyroscopes. The various sensing elements are manufactured using specialized micromachining processes, while the IC interfaces are developed using CMOS technology that allows the design of a dedicated circuit which is trimmed to better match the characteristics of the sensing element.

The LSM6DSM is available in a small plastic land grid array (LGA) package of 2.5 x 3.0 x 0.83 mm to address ultra-compact solutions.

2 Embedded low-power features

The LSM6DSM has been designed to be fully compliant with Android, featuring the following on-chip functions:

- 4 kbyte data buffering
  - 100% efficiency with flexible configurations and partitioning
  - Possibility to store timestamp
- Event-detection interrupts (fully configurable):
  - Free-fall
  - Wakeup
  - 6D orientation
  - Click And double-click sensing
  - Activity / inactivity recognition
- Specific IP blocks with negligible power consumption and high-performance:
  - Pedometer functions: step detector and step counters
  - Tilt (refer to *Section 2.1: Tilt detection* for additional information
  - Absolute Wrist Tilt (refer to *Section 2.2: Absolute wrist tilt* for additional information)
  - Significant Motion Detection
- Sensor hub
  - Up to 6 total sensors: 2 internal (accelerometer and gyroscope) and 4 external sensors
- Data rate synchronization with external trigger for reduced sensor access and enhanced fusion

2.1 Tilt detection

The tilt function helps to detect activity change and has been implemented in hardware using only the accelerometer to achieve both the targets of ultra-low power consumption and robustness during the short duration of dynamic accelerations.

It is based on a trigger of an event each time the device's tilt changes. For a more customized user experience, in the LSM6DSM the tilt function is configurable through:

- a programmable average window
- a programmable average threshold

The tilt function can be used with different scenarios, for example:

a) Triggers when phone is in a front pants pocket and the user goes from sitting to standing or standing to sitting;

b) Doesn’t trigger when phone is in a front pants pocket and the user is walking, running or going upstairs.

2.2 Absolute wrist tilt

The LSM6DSM implements in hardware the Absolute Wrist Tilt (AWT) function which allows detecting when the angle between a selectable accelerometer semi-axis and the horizontal plane becomes higher than a specific user-selectable value.

Configurable threshold and latency parameters are associated with the AWT function: the threshold parameter defines the amplitude of the tilt angle; the latency parameter defines the minimum duration of the AWT event to be recognized. The AWT interrupt signal is generated if the tilt angle is higher than the threshold angle for a period of time equal to or greater than the latency period.

The AWT function is based on the accelerometer sensor only and works at 26 Hz, so the accelerometer ODR must be set at a value of 26 Hz or higher.

By default, the AWT algorithm is applied to the positive X-axis.

In order to enable the AWT function it is necessary to set to 1 both the FUNC_EN bit and the WRIST_TILT_EN bit of *CTRL10_C (19h)*.

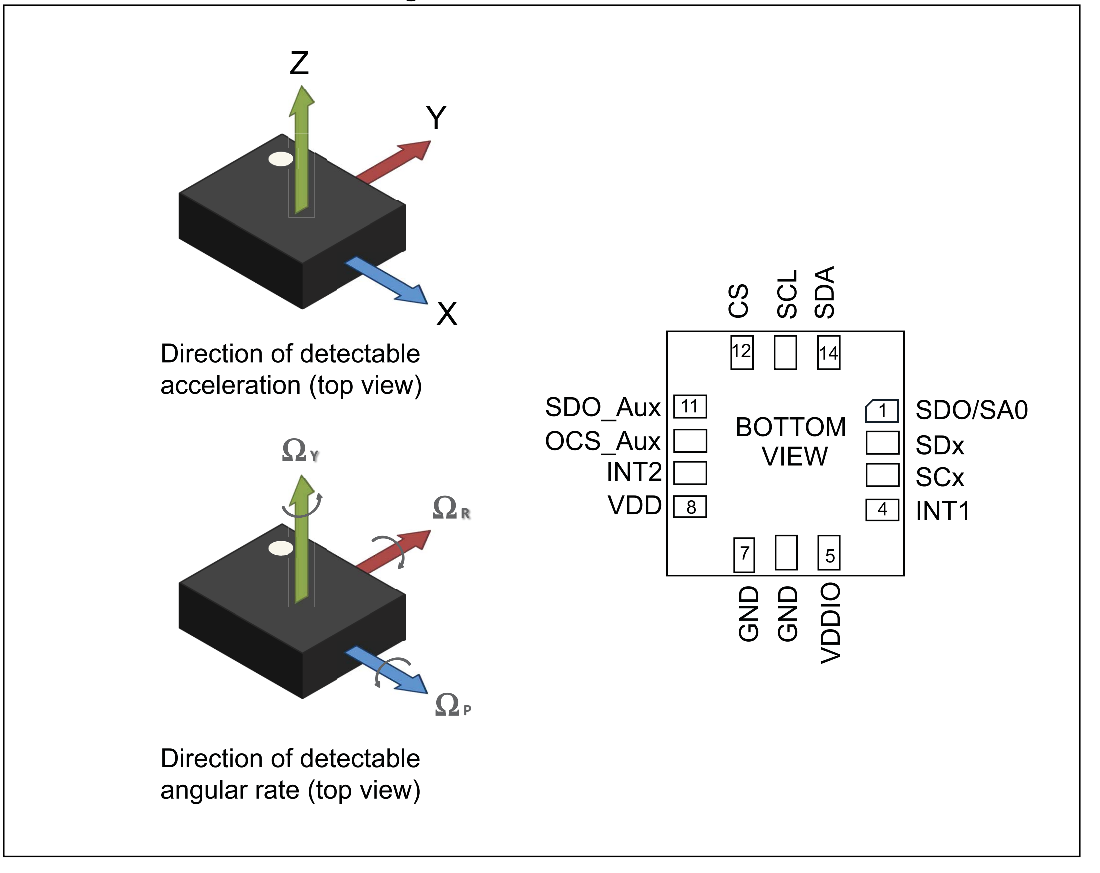
The AWT interrupt signal can be driven to the INT2 interrupt pin by setting to 1 the INT2_WRIST_TILT bit of the *DRDY_PULSE_CFG (0Bh)* register; it can also be checked by reading the WRIST_TILT_IA bit of the *FUNC_SRC2 (54h)* register (it will also clear the interrupt signal if latched).

WRIST_TILT_IA (55h) is the status register to be used to detect which axis has triggered the AWT event (not applicable when using one axis side only).

The full description and an example is given in the dedicated application note.

3 Pin description

Figure 1. Pin connections

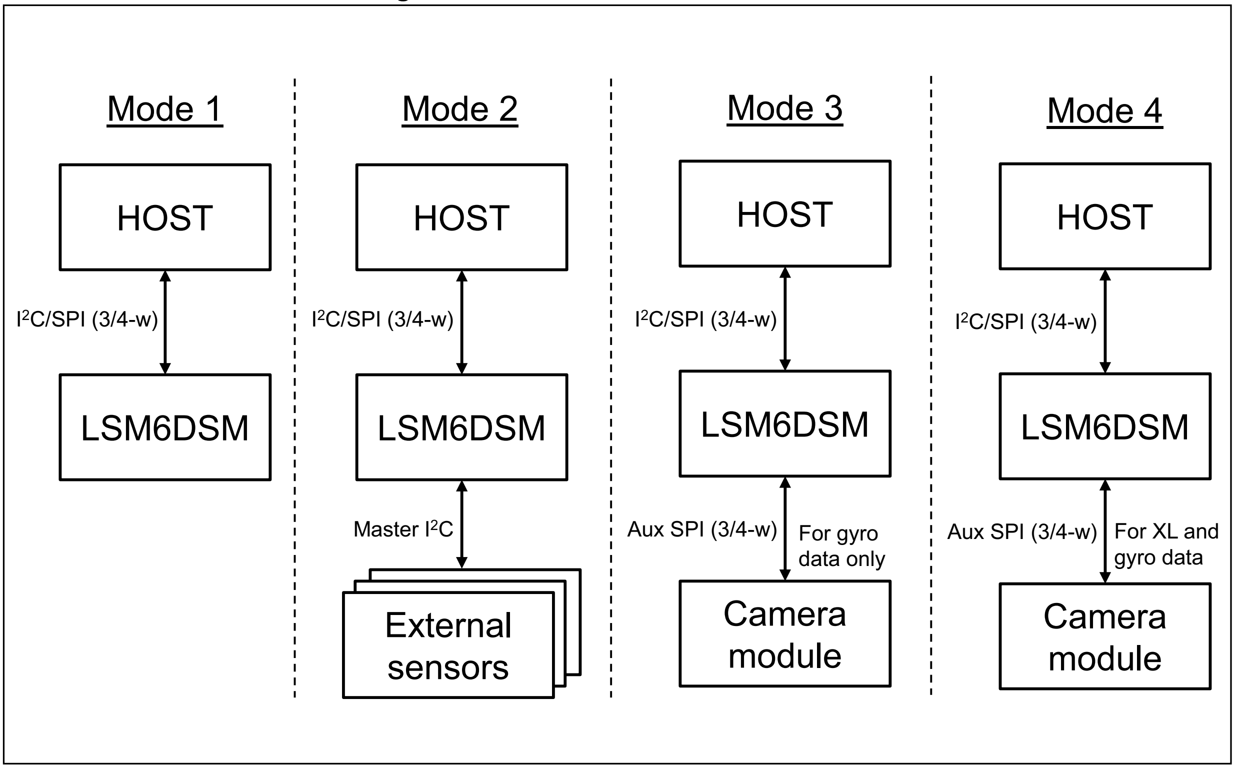


3.1 Pin connections

The LSM6DSM offers flexibility to connect the pins in order to have four different mode connections and functionalities. In detail:

- **Mode 1**: I^2C slave interface or SPI (3- and 4-wire) serial interface is available;
- **Mode 2**: I^2C slave interface or SPI (3- and 4-wire) serial interface and I^2C interface master for external sensor connections are available;
- **Mode 3:** I^2C slave interface or SPI (3- and 4-wire) serial interface is available for the application processor interface while an auxiliary SPI (3- and 4-wire) serial interface for external sensor connections (i.e. camera module) is available for the gyroscope ONLY;
- **Mode 4:** I^2C slave interface or SPI (3- and 4-wire) serial interface is available for the application processor interface while an auxiliary SPI (3- and 4-wire) serial interface for external sensor connections (i.e. camera module with hybrid OIS) is available for the accelerometer and gyroscope.

Figure 2. LSM6DSM connection modes



In the following table each mode is described for the pin connections and function.

Table 2. Pin description

Pin#	Name	Mode 1 function	Mode 2 function	Mode 3 / Mode 4 function
1	SDO/SA0	SPI 4-wire interface serial data output (SDO) I^{2}C least significant bit of the device address (SA0)	SPI 4-wire interface serial data output (SDO) I^{2}C least significant bit of the device address (SA0)	SPI 4-wire interface serial data output (SDO) I^{2}C least significant bit of the device address (SA0)
2	SDx	Connect to VDDIO or GND	I^{2}C serial data master (MSDA)	Auxiliary SPI 3/4-wire interface serial data input (SDI) and SPI 3-wire serial data output (SDO)
3	SCx	Connect to VDDIO or GND	I^{2}C serial clock master (MSCL)	Auxiliary SPI 3-wire interface serial port clock (SPC_Aux)
4	INT1	Programmable interrupt 1		
5	VDDIO[1]	Power supply for I/O pins		
6	GND	0 V supply		
7	GND	0 V supply		
8	VDD[1]	Power supply		
9	INT2	Programmable interrupt 2 (INT2) / Data enable (DEN)	Programmable interrupt 2 (INT2)/ Data enable (DEN)/ I^{2}C master external synchronization signal (MDRDY)	Programmable interrupt 2 (INT2)/ Data enable (DEN)
10	OCS_Aux	Leave unconnected[2]	Leave unconnected[2]	Auxiliary SPI 3/4-wire interface enable
11	SDO_Aux	Connect to VDD_IO or leave unconnected[2]	Connect to VDD_IO or leave unconnected[2]	Auxiliary SPI 3-wire interface: leave unconnected[2] Auxiliary SPI 4-wire interface: serial data output (SDO_Aux)
12	CS	I^{2}C/SPI mode selection (1: SPI idle mode / I^{2}C communication enabled; 0: SPI communication mode / I^{2}C disabled)	I^{2}C/SPI mode selection (1: SPI idle mode / I^{2}C communication enabled; 0: SPI communication mode / I^{2}C disabled)	I^{2}C/SPI mode selection (1: SPI idle mode / I^{2}C communication enabled; 0: SPI communication mode / I^{2}C disabled)
13	SCL	I^{2}C serial clock (SCL) SPI serial port clock (SPC)	I^{2}C serial clock (SCL) SPI serial port clock (SPC)	I^{2}C serial clock (SCL) SPI serial port clock (SPC)
14	SDA	I^{2}C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)	I^{2}C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)	I^{2}C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)

1. Recommended 100 nF filter capacitor.
2. Leave pin electrically unconnected and soldered to PCB.

4 Module specifications

4.1 Mechanical characteristics

@ Vdd = 1.8 V, T = 25 °C unless otherwise noted.

Table 3. Mechanical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.(1)	Max.	Unit
LA_FS	Linear acceleration measurement range			±2		*g*
				±4		
				±8		
				±16		
G_FS	Angular rate measurement range			±125		dps
				±245		
				±500		
				±1000		
				±2000		
LA_So	Linear acceleration sensitivity(2)	FS = ±2		0.061		m*g*/LSB
		FS = ±4		0.122		
		FS = ±8		0.244		
		FS = ±16		0.488		
G_So	Angular rate sensitivity(2)	FS = ±125		4.375		mdps/LSB
		FS = ±245		8.75		
		FS = ±500		17.50		
		FS = ±1000		35		
		FS = ±2000		70		
G_So%	Sensitivity tolerance(3)	at component level		±1		%
LA_SoDr	Linear acceleration sensitivity change vs. temperature(4)	from -40° to +85°		±0.01		%/°C
G_SoDr	Angular rate sensitivity change vs. temperature(4)	from -40° to +85°		±0.007		%/°C
LA_TyOff	Linear acceleration zero-*g* level offset accuracy(5)			±40		m*g*
G_TyOff	Angular rate zero-rate level(5)			±3		dps
LA_OffDr	Linear acceleration zero-*g* level change vs. temperature(4)			±0.1		m*g*/ °C
G_OffDr	Angular rate typical zero-rate level change vs. temperature(4)			±0.015		dps/°C

Table 3. Mechanical characteristics (continued)

Symbol	Parameter	Test conditions	Min.	Typ.[1]	Max.	Unit
Rn	Rate noise density in high-performance mode[6]			3.8		mdps/√Hz
RnRMS	Gyroscope RMS noise in normal/low-power mode[7]			75		mdps
An	Acceleration noise density in high-performance mode[8]	FS = ±2 *g*		90		μ*g*/√Hz
		FS = ±4 *g*		90		
		FS = ±8 *g*		90		
		FS = ±16 *g*		130		
RMS	Acceleration RMS noise in normal/low-power mode[9][10]	FS = ±2 *g*		1.8		m*g*(RMS)
		FS = ±4 *g*		2.0		
		FS = ±8 *g*		2.4		
		FS = ±16 *g*		3.0		
LA_ODR	Linear acceleration output data rate			1.6[11] 12.5 26 52 104 208 416 833 1666 3332 6664		Hz
G_ODR	Angular rate output data rate			12.5 26 52 104 208 416 833 1666 3332 6664		
Vst	Linear acceleration self-test output change[12][13][14]		90		1700	m*g*
	Angular rate self-test output change[15][16]	FS = 245 dps	20		80	dps
		FS = 2000 dps	150		700	dps
Top	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed.
2. Sensitivity values after factory calibration test and trimming.
3. Subject to change.

4. Measurements are performed in a uniform temperature setup and they are based on characterization data in a limited number of samples. Not measured during final test for production.
5. Values after factory calibration test and trimming.
6. Gyroscope rate noise density in high-performance mode is independent of the ODR and FS setting.
7. Gyroscope RMS noise in normal/low-power mode is independent of the ODR and FS setting.
8. Accelerometer noise density in high-performance mode is independent of the ODR.
9. Accelerometer RMS noise in normal/low-power mode is independent of the ODR.
10. Noise RMS related to BW = ODR /2 (for ODR /9, typ value can be calculated by Typ *0.6).
11. This ODR is available when accelerometer is in low-power mode.
12. The sign of the linear acceleration self-test output change is defined by the STx_XL bits in *CTRL5_C (14h)*, *Table 64* for all axes.
13. The linear acceleration self-test output change is defined with the device in stationary condition as the absolute value of: OUTPUT[LSb] (self-test enabled) - OUTPUT[LSb] (self-test disabled). 1LSb = 0.061 m*g* at ±2 *g* full scale.
14. Accelerometer self-test limits are full-scale independent.
15. The sign of the angular rate self-test output change is defined by the STx_G bits in *CTRL5_C (14h)*, *Table 63* for all axes.
16. The angular rate self-test output change is defined with the device in stationary condition as the absolute value of: OUTPUT[LSb] (self-test enabled) - OUTPUT[LSb] (self-test disabled). 1LSb = 70 mdps at ±2000 dps full scale.